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(54) **SEMICONDUCTOR PACKAGE AND METHOD OF MANUFACTURING THE SEMICONDUCTOR PACKAGE**

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**ABSTRACT**

A semiconductor package includes a lower redistribution wiring layer having a first region and a second region adjacent the first region and including first redistribution wirings; a semiconductor chip on the first region of the lower redistribution wiring layer and electrically connected to the first redistribution wirings; a sealing member on a side surface of the semiconductor chip and on the lower redistribution wiring layer; a plurality of vertical conductive structures penetrating the sealing member on the second region of the lower redistribution wiring layer and electrically connected to the first redistribution wirings; a marking pattern on the semiconductor chip; seed layer pads on respective end portions of the vertical conductive structures that are exposed by the sealing member at an upper surface thereof; and an upper redistribution wiring layer on the sealing member and the marking pattern and including second redistribution wirings.

